

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of	:	Confirmation No.: 7364
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TSUKASA MATSUDA et al.	:	Group Art Unit: 1762
	:	
Appln. No.: 10/673,910	:	Examiner: STOUFFER, Kelly M.
	:	
Filed: September 30, 2003	:	
	:	
FOR: METHOD FOR DEPOSITING METAL LAYERS USING SEQUENTIAL FLOW DEPOSITION		

May 25, 2007

AMENDMENT

Mail Stop Amendment
United States Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In response to the Final Office Action dated March 20, 2007, please amend the above-captioned patent application as follows: